

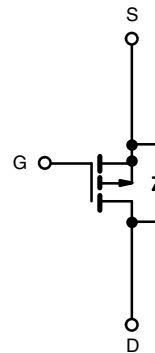
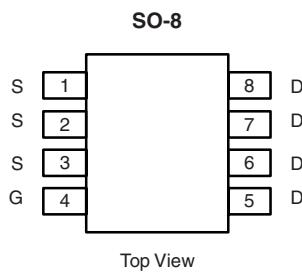


P-Channel 2.5-V (G-S) MOSFET

PRODUCT SUMMARY		
V _{DS} (V)	r _{DS(on)} (Ω)	I _D (A)
- 20	0.011 at V _{GS} = - 10 V	- 13.7
	0.014 at V _{GS} = - 4.5 V	- 12.3
	0.020 at V _{GS} = - 2.5 V	- 10.3



RoHS
COMPLIANT



Ordering Information: Si4463BDY-T1-E3 (Lead (Pb)-free)

P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted				
Parameter	Symbol	10 sec	Steady State	Unit
Drain-Source Voltage	V _{DS}	- 20		V
Gate-Source Voltage	V _{GS}	± 12		
Continuous Drain Current (T _J = 150 °C) ^a	I _D	T _A = 25 °C	- 13.7	- 9.8
		T _A = 70 °C	- 11.1	- 7.9
Pulsed Drain Current	I _{DM}	- 50		A
Continuous Source Current (Diode Conduction) ^a	I _S	- 2.7	- 1.36	
Maximum Power Dissipation ^a	P _D	T _A = 25 °C	3.0	1.5
		T _A = 70 °C	1.9	0.95
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150		°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^a	t ≤ 10 sec	R _{thJA}	35	42	°C/W
	Steady State		70	84	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	17	21	

Notes:

a. Surface Mounted on 1" x 1" FR4 Board.



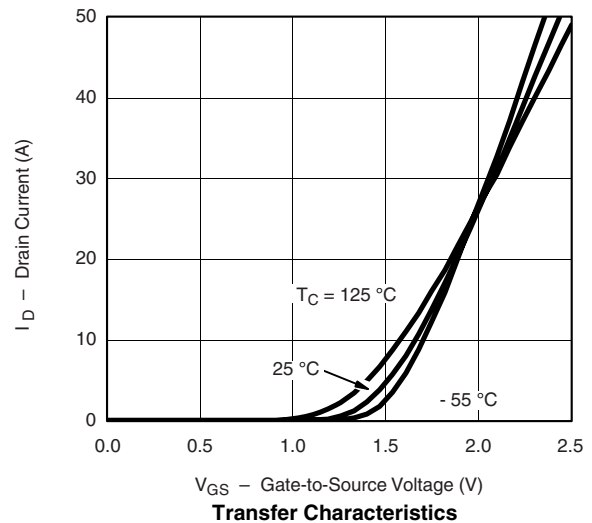
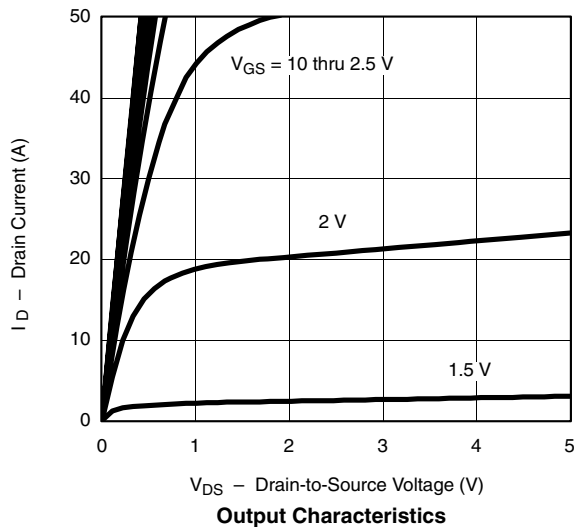
SPECIFICATIONS $T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted						
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\text{ }\mu\text{A}$	-0.6		-1.4	V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = \pm 12\text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -20\text{ V}, V_{GS} = 0\text{ V}$			-1	μA
		$V_{DS} = -20\text{ V}, V_{GS} = 0\text{ V}, T_J = 70\text{ }^\circ\text{C}$			-10	
On-State Drain Current ^a	$I_{D(on)}$	$V_{DS} = -5\text{ V}, V_{GS} = -4.5\text{ V}$	-30			A
Drain-Source On-State Resistance ^a	$r_{DS(on)}$	$V_{GS} = -10\text{ V}, I_D = -13.7\text{ A}$		0.0085	0.011	Ω
		$V_{GS} = -4.5\text{ V}, I_D = -12.3\text{ A}$		0.010	0.014	
		$V_{GS} = -2.5\text{ V}, I_D = -5\text{ A}$		0.015	0.020	
Forward Transconductance ^a	g_{fs}	$V_{DS} = -10\text{ V}, I_D = -13.7\text{ A}$		44		S
Diode Forward Voltage ^a	V_{SD}	$I_S = -2.7\text{ A}, V_{GS} = 0\text{ V}$		-0.7	-1.1	V
Dynamic^b						
Total Gate Charge	Q_g	$V_{DS} = -10\text{ V}, V_{GS} = -4.5\text{ V}, I_D = -13.7\text{ A}$		37	56	nC
Gate-Source Charge	Q_{gs}		8.7			
Gate-Drain Charge	Q_{gd}		11			
Gate Resistance	R_g	$f = 1\text{ MHz}$		2.7		Ω
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = -10\text{ V}, R_L = 10\text{ }\Omega$ $I_D \cong -1\text{ A}, V_{GEN} = -4.5\text{ V}, R_g = 6\text{ }\Omega$		35	55	ns
Rise Time	t_r		60	90		
Turn-Off Delay Time	$t_{d(off)}$		115	170		
Fall Time	t_f		75	115		
Source-Drain Reverse Recovery Time	t_{rr}		$I_F = -2.3\text{ A}, di/dt = 100\text{ A}/\mu\text{s}$		50	

Notes:

- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.
- b. Guaranteed by design, not subject to production testing.

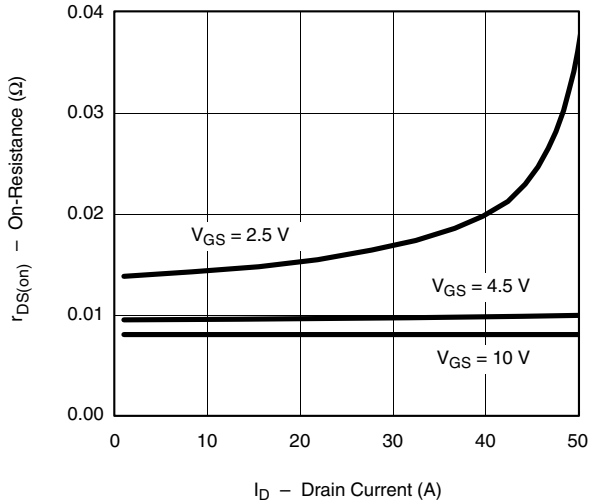
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS $25\text{ }^\circ\text{C}$, unless otherwise noted

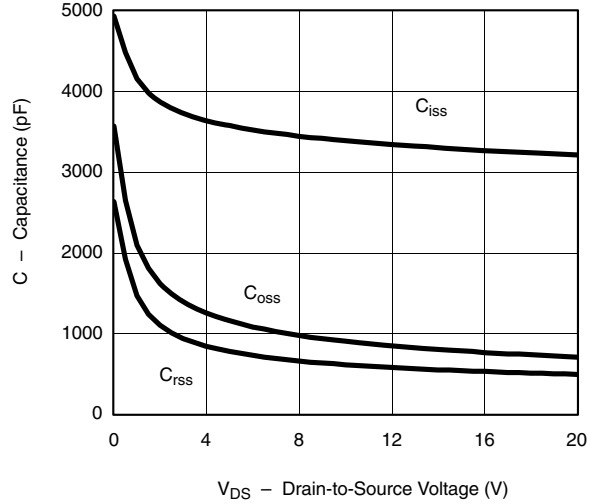




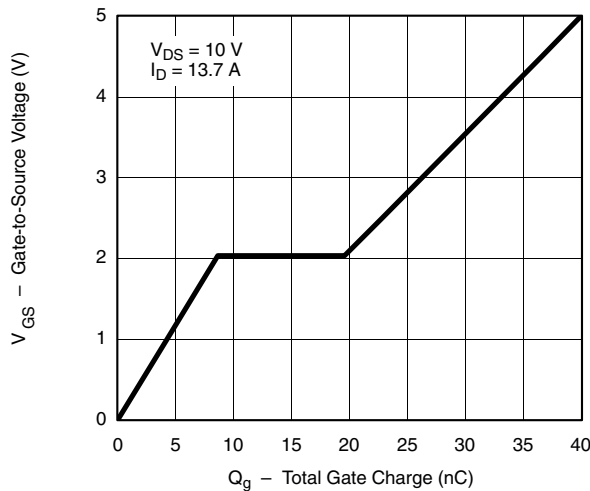
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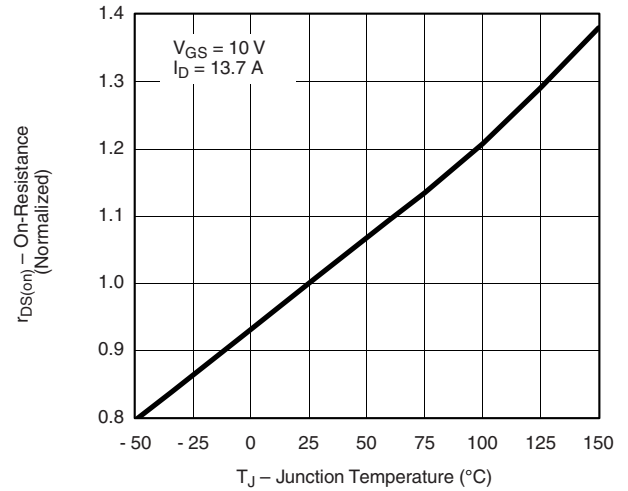
On-Resistance vs. Drain Current



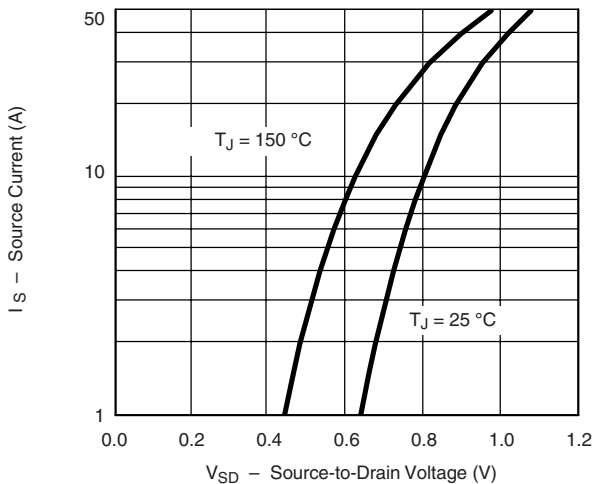
Capacitance



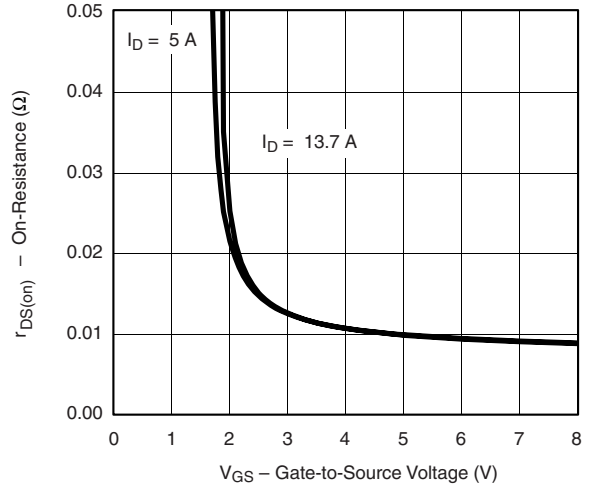
Gate Charge



On-Resistance vs. Junction Temperature



Source-Drain Diode Forward Voltage



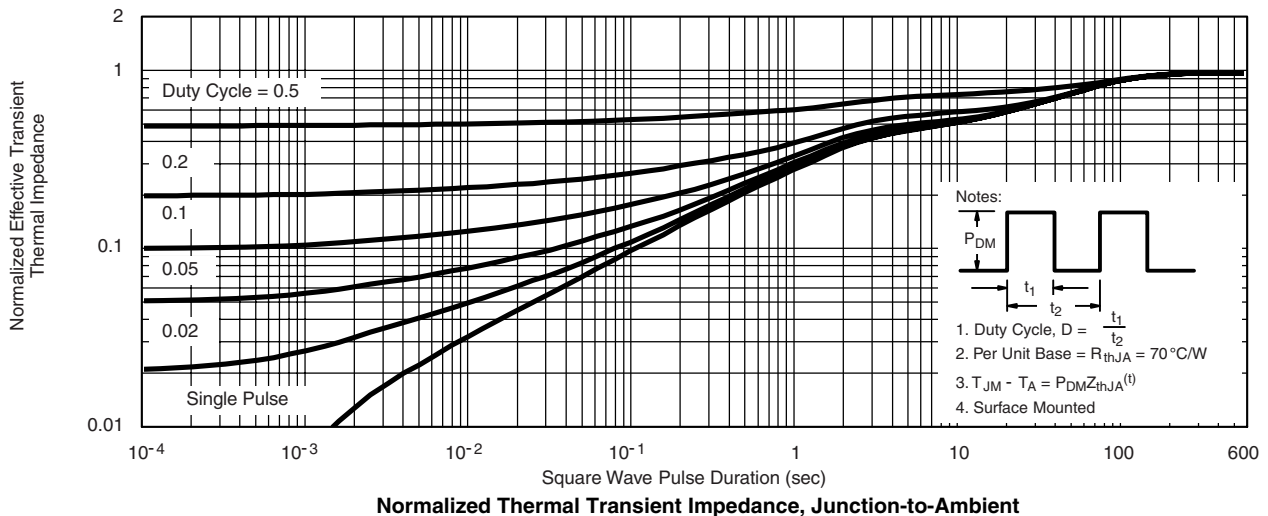
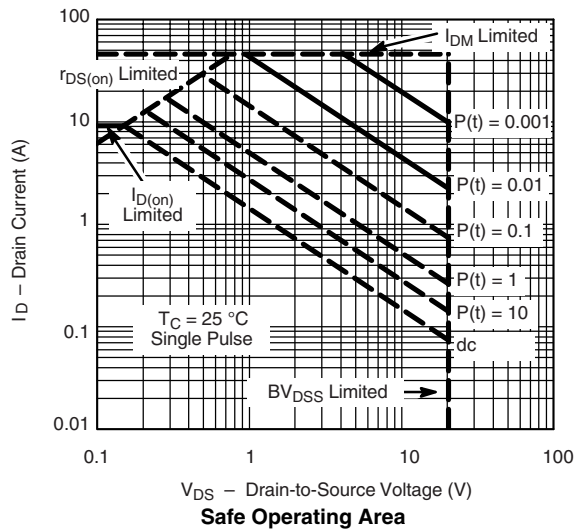
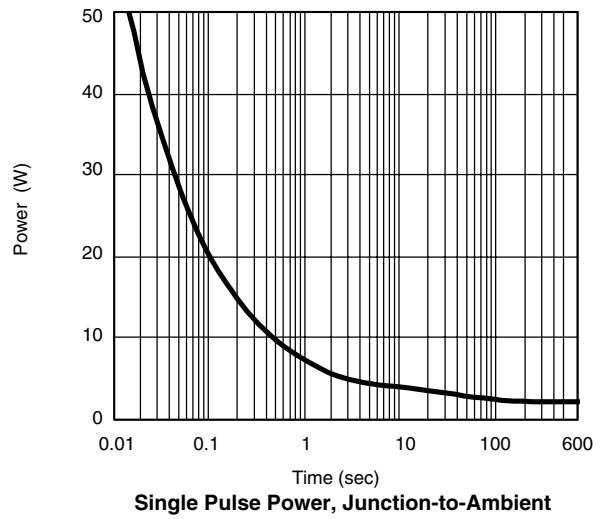
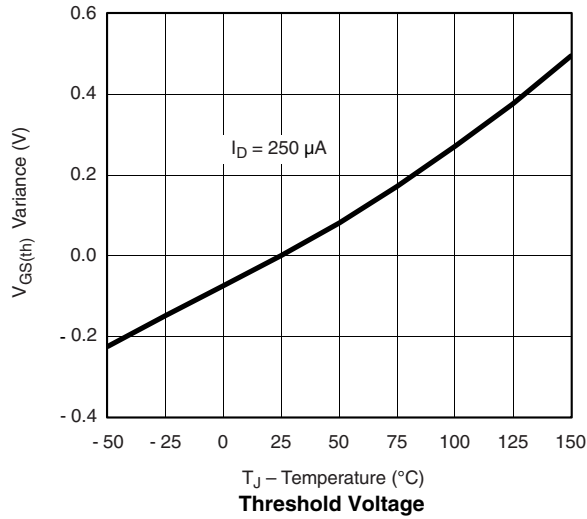
On-Resistance vs. Gate-to-Source Voltage

Si4463BDY

Vishay Siliconix

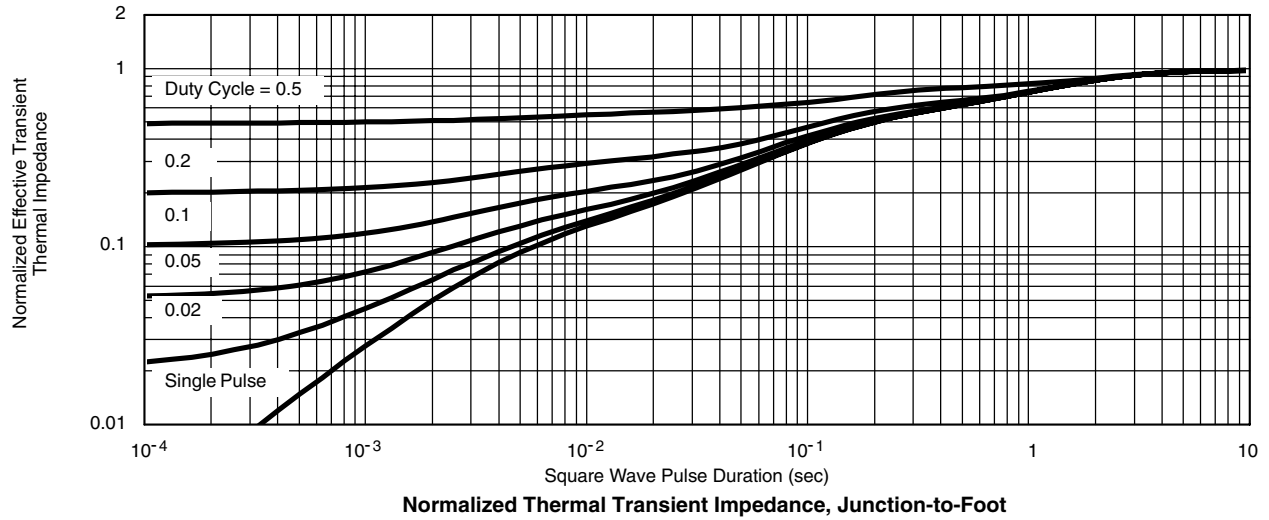


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



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